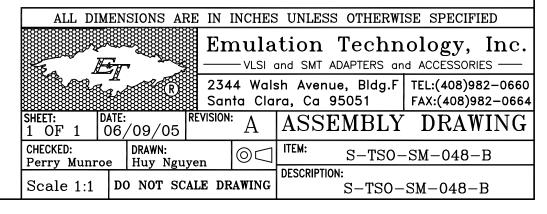


## SPECIFICATIONS:

- FOR OEM, PROGRAMMING, PROTOTYPING AND TEST APPLICATIONS
- SURFACE MOUNT ZERO-INSERTION FORCE
- LAND-PAD FOOTPRINT COMMON FOR PACKAGE AND SOCKET
- EFFORTLESS PACKAGE LOADING AND UNLOADING
- BODY, LID AND LOCK MATERIAL: LCP
- TERMÍNAL MATERIAL: COPPER ALLOY, WITH PALLADIUM OVER NICKEL PLATING
- MINIMUM INSERTION/WITHDRAWL CYCLES: 50
- TEMPERATURE RANGE: -55°C TO + 105°C
- CURRENT RATING: 0.5 AMP
- FLAMMABILITY: 940V-0
- VERY POSITIVE LOCKING LID DESIGN

PACKAGE SPECIFICATIONS
PIN COUNT $= 48$
LEAD PITCH = 0.50mm
PACKAGE WIDTH= 18.40mm

	DIM A		DIM B		DIM C	
ET PACKAGE CODE	mm	inches	mm	inches	mm	inches
48-TS01	13.85	.545	11.50	.453	15.62	.615



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